SIDE LOOK PACKAGE
SOLID STATE LAMP

MSL-824MW

Description

The MSL-824MW, a white source color device, is made with advanced InGaN on SiC chip. The package is mixing epoxy and phosphor within white plastic.

Applications

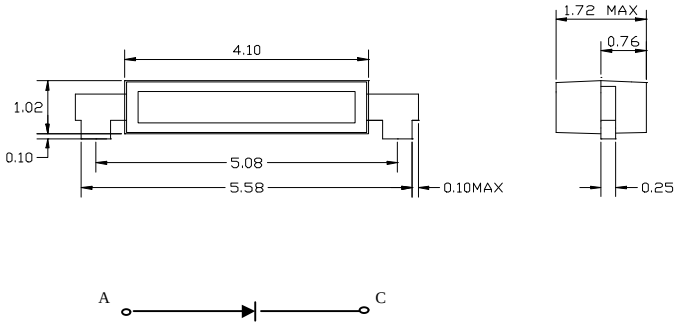
- LCD backlighting
- Symbol backlighting
- Front panel indicator

Features

- High performance
- Excellent chip to chip consistency
- Uniform radiation pattern

Package Dimensions

Units : mm



Notes :
1. All dimensions are in millimeters.
2. Tolerance is ± 0.1 mm unless otherwise noted.
3. Lead plating is minimum 80 mirco inch of silver.

Absolute Maximum Ratings

@ T_A=25°C

Parameter	Symbol	Maximum Rating	Unit
Power Dissipation	P	100	mW
Continuous Forward Current	I_F	25	μA
Reverse Current (V_R=5V)	I_R	100	μA
Operating Temperature Range	T_{opr}	-20°C to +85°C	
Storage Temperature Range	T_{stg}	-40°C to +100°C	
Electrostatic Discharge Threshold (HBM)	E_{ot}	1000	V

Optical-Electrical Characteristics

@ T_A=25°C

Parameter	Test Conditions	Symbol	Min .	Typ .	Max .	Unit .
Luminous Intensity	I_F=20mA	I_V	-	150	-	mcd
Forward Voltage	I_F=20mA	V_F	-	3.5	4.1	V
Reverse Current	V_R=5V	I_R	-	-	100	μA
Chromaticity	I_F=20mA	x/y		0.33/0.33		
Viewing Angle	I_F=20mA	$2\theta_{1/2}$	-	110	-	deg.

Typical Optical-Electrical Characteristic Curves

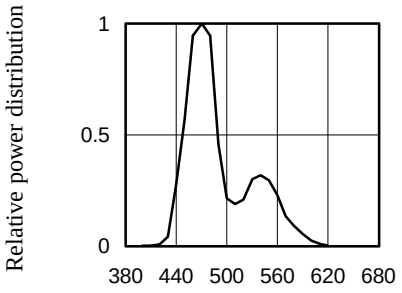


FIG.1 RELATIVE LUMINOUS INTENSITY

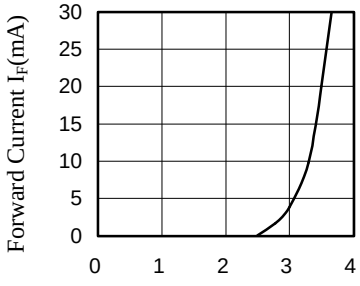


FIG.2 FORWARD CURRENT VS. FORWARD VOLTAGE

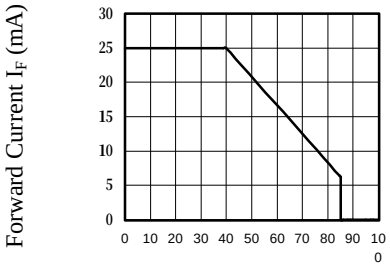


FIG.3 FORWARD CURRENT VS. AMBIENT TEMPERATURE

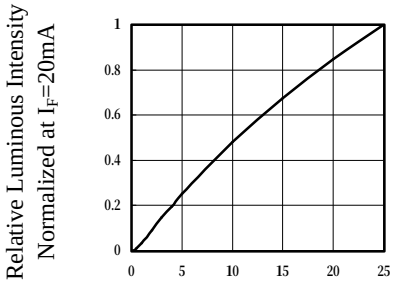


FIG.4 RELATIVE LUMINOUS INTENSITY

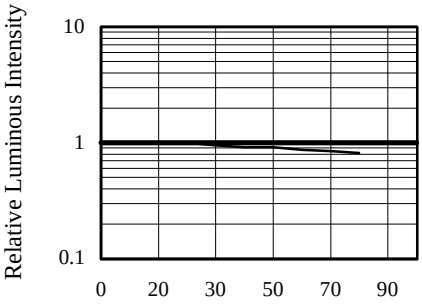


FIG.5 RELATIVELUMINOUS INTENSITY VS. AMBIENT TEMPERATURE

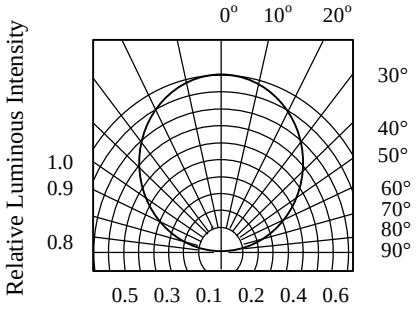


FIG.6 RADIATION DIAGRAM